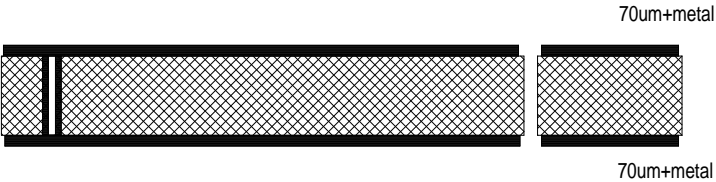
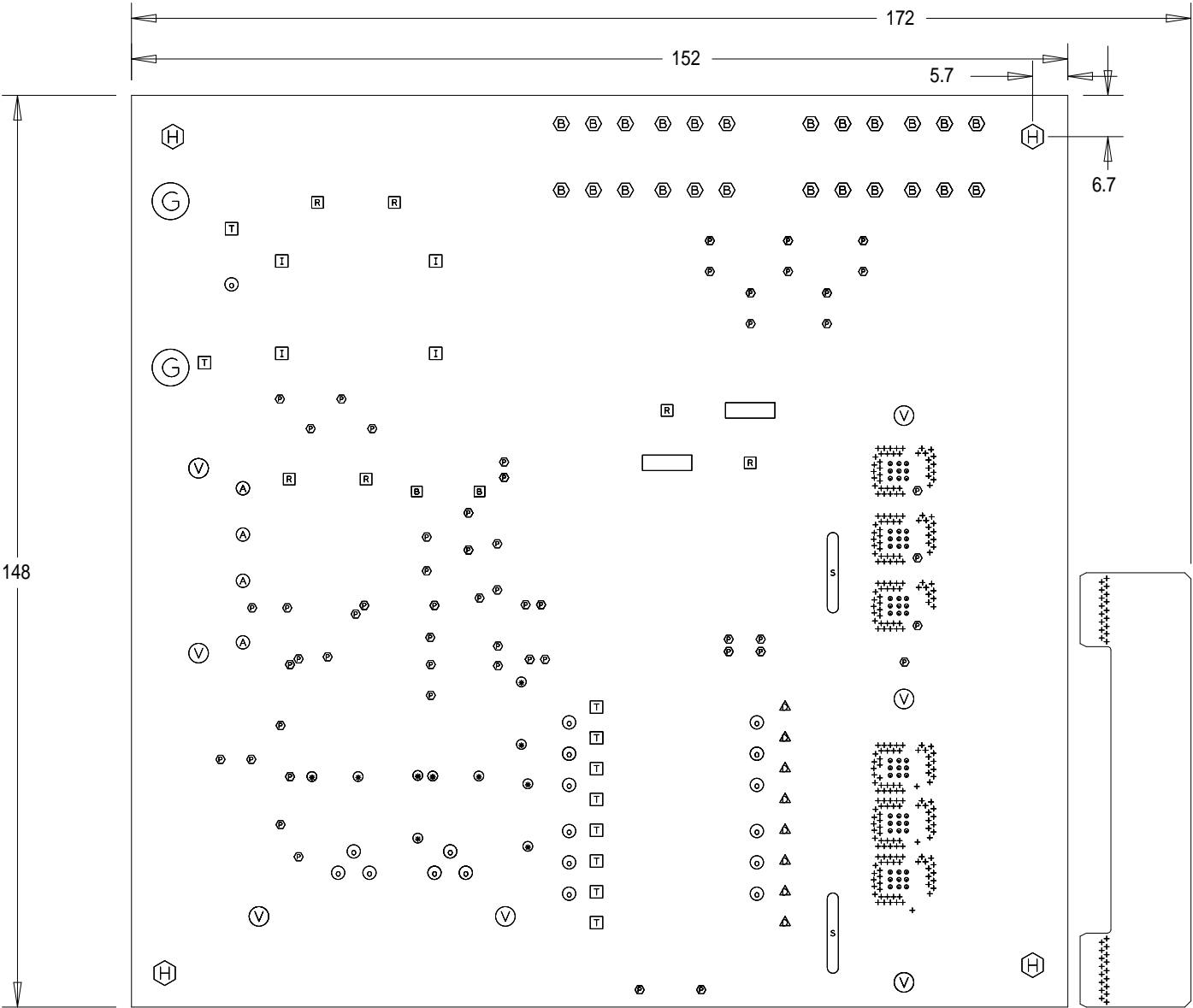


SPEC:

COMPLIANT RoHS DIRECTIVE 2011/65/UE

MATERIAL	FR4 IMPROVED (low CTE)
BOARD THICKNESS	1.6mm /63mils
STACKUP	DFTM / 2layers
MINIMAL GAP	300um /12mils
MINIMAL SLIVER	300um /12mils
COPPER THICKNESS	105um(3oz)at END
FINISH THICKNESS	CHEMICAL NiAu
SOLDER MASK	GREEN TOP&BOT
SILKSCREEN	WHITE TOP&BOT
ALL BOARD ELECTRICALLY TESTED	
MANUFACTURE 'S LOGO & DATECODE MARKED ON BOTTOM SOLDERMASK	

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILLIMETERS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	0.3	+0.1/-0.05	PLATED	54
+	0.4	+0.1/-0.05	PLATED	267
⊙	0.8	+0.1/-0.05	PLATED	56
⊙	1.0	+0.1/-0.05	PLATED	10
⊙	1.1	+0.1/-0.05	PLATED	2
⊙	1.2	+0.1/-0.05	PLATED	6
⊙	1.3	+0.1/-0.05	PLATED	4
⊙	1.35	+0.1/-0.05	PLATED	8
⊙	1.4	+0.1/-0.05	PLATED	10
⊙	1.6	+0.1/-0.05	PLATED	19
⊙	1.9	+0.1/-0.05	PLATED	4
⊙	2.6	+0.1/-0.1	PLATED	24
⊙	3.2	+0.1/-0.1	PLATED	7
⊙	4.0	+0.1/-0.1	PLATED	4
⊙	6.0	+0.1/-0.1	NO	2
⊙	8.0x2.5	+0.1/-0.1	PLATED	2
⊙	13.0x1.8	+0.1/-0.1	PLATED	2



2.0 1.0	W11/2019 W23/2018	
indice	Description	Date
Controle par :		Autorise par:
ON semiconductor		Definition CUT DRILL DRAWING PLAN PRECAGE DETOURAGE
Board: NCL30125 300W-EVB		Subc. DYPE TECH
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